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6/4/02**REPLY UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 1765**ATTORNEY'S DOCKET NO. 042390.P6147PATENT**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE THE

APPLICATION OF: Anne E. Miller et al.

APPLICATION NO.: 09/280,268

FILED: March 29, 1999

TITLE: A CERIC-ION SLURRY FOR USE
IN CHEMICAL-MECHANICAL
POLISHING

ART UNIT: 1765

EXAMINER: Deo, D.

RESPONSE TO FINAL OFFICE ACTIONBox AF
Commissioner for Patents
Washington, D.C. 20231FAX RECEIVED
JUN 3 2002
GROUP 1700
Official

The following amendments and remarks are respectfully submitted in response to the Final Office Action mailed on May 16, 2002. Examination of the present application is respectfully requested.

IN THE CLAIMS

Please amend claims 1 and 26, cancel claims 6, 10, and 11 and consider claims 1-5, 7-9, 12-14 and 26-29 re-presented below.

1. (Twice Amended) A chemical-mechanical polishing slurry for a copper based metal layer on a semiconductor substrate, the chemical-mechanical polishing slurry comprising:

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